

1.5A Dual High-Speed Power MOSFET Drivers

Features

- High-Speed Switching (C_L = 1000pF): 30nsec
- High Peak Output Current: 1.5A
- · High Output Voltage Swing
 - V_{DD} -25mV
 - GND +25mV
- Low Input Current (Logic "0" or "1"): 1μΑ
- TTL/CMOS Input Compatible
- Available in Inverting and Noninverting Configurations
- · Wide Operating Supply Voltage
 - 4.5V to 18V
- Current Consumption
 - Inputs Low 0.4mA
 - Inputs High 8mA
- Single Supply Operation
- Low Output Impedance: 6Ω
- Pinout Equivalent of DS0026 and MMH0026
- Latch-Up Resistant: Withstands > 500mA Reverse Current
- ESD Protected: 2kV

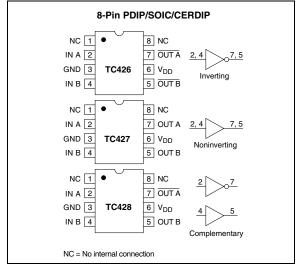
Applications

- Switch Mode Power Supplies
- Pulse Transformer Drive
- Clock Line Driver
- · Coax Cable Driver

Device Selection Table

Part Number	Package	Configuration	Temp. Range
TC426COA	8-Pin SOIC	Inverting	0°C to +70°C
TC426CPA	8-Pin PDIP	Inverting	0°C to +70°C
TC426EOA	8-Pin SOIC	Inverting	-40°C to +85°C
TC426EPA	8-Pin PDIP	Inverting	-40°C to +85°C
TC426IJA	8-Pin CERDIP	Inverting	-25°C to +85°C
TC426MJA	8-Pin CERDIP	Inverting	-55°C to +125°C
TC427COA	8-Pin SOIC	Noninverting	0°C to +70°C
TC427CPA	8-Pin PDIP	Noninverting	0°C to +70°C
TC427EOA	8-Pin SOIC	Noninverting	-40°C to +85°C
TC427EPA	8-Pin PDIP	Noninverting	-40°C to +85°C
TC427IJA	8-Pin CERDIP	Noninverting	-25°C to +85°C
TC427MJA	8-Pin CERDIP	Noninverting	-55°C to +125°C
TC428COA	8-Pin SOIC	Complementary	0°C to +70°C
TC428CPA	8-Pin PDIP	Complementary	0°C to +70°C
TC428EOA	8-Pin SOIC	Complementary	-40°C to +85°C
TC428EPA	8-Pin PDIP	Complementary	-40°C to +85°C
TC428IJA	8-Pin CERDIP	Complementary	-25°C to +85°C
TC428MJA	8-Pin CERDIP	Complementary	-55°C to +125°C

Package Type



General Description

The TC426/TC427/TC428 are dual CMOS high-speed drivers. A TTL/CMOS input voltage level is translated into a rail-to-rail output voltage level swing. The CMOS output is within 25mV of ground or positive supply.

The low impedance, high-current driver outputs swing a 1000pF load 18V in 30nsec. The unique current and voltage drive qualities make the TC426/TC427/TC428 ideal power MOSFET drivers, line drivers, and DC-to-DC converter building blocks.

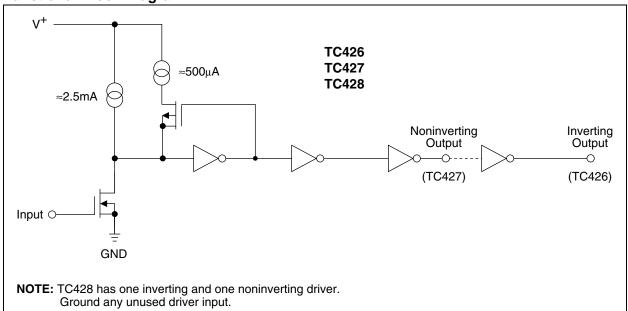
Input logic signals may equal the power supply voltage. Input current is a low $1\mu A,$ making direct interface to CMOS/bipolar switch-mode power supply control ICs possible, as well as open-collector analog comparators.

Quiescent power supply current is 8mA maximum. The TC426 requires 1/5 the current of the pin-compatible bipolar DS0026 device. This is important in DC-to-DC converter applications with power efficiency constraints and high-frequency switch-mode power supply applications. Quiescent current is typically 6mA when driving a 1000pF load 18V at 100kHz.

The inverting TC426 driver is pin-compatible with the bipolar DS0026 and MMH0026 devices. The TC427 is noninverting; the TC428 contains an inverting and noninverting driver.

Other pin compatible driver families are the TC1426/TC1427/TC1428, TC4426/TC4427/TC4428 and TC4426A/TC4427A/TC4428A.

Functional Block Diagram



1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings*

Supply Voltage	+20V
Input Voltage, Any Terminal	
V _{DD} + 0.	3V to GND - 0.3V
Power Dissipation (T _A ≤ 70°C)	
PDIP	730mW
CERDIP	800mW
SOIC	470mW
Derating Factor	
PDIP	8mW/°C
CERDIP	6.4mW/°C
SOIC	
Operating Temperature Range	
C Version	0°C to +70°C
I Version	
E Version	
M Version	
Storage Temperature Range	65°C to +150°C

*Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

TC426/TC427/TC428 ELECTRICAL SPECIFICATIONS

Electrical Characteristics: T _A = +25°C with 4.5V ≤ V _{DD} ≤ 18V, unless otherwise noted.						
Symbol	Parameter	Min	Тур	Max	Units	Test Conditions
Input						
V _{IH}	Logic 1, High Input Voltage	2.4	_	_	V	
V _{IL}	Logic 0, Low Input Voltage	_	_	0.8	V	
I _{IN}	Input Current	-1	_	1	μΑ	$0V \le V_{IN} \le V_{DD}$
Output						
V _{OH}	High Output Voltage	V _{DD} - 0.025	_	_	V	
V _{OL}	Low Output Voltage	_	_	0.025	V	
R _{OH}	High Output Resistance	_	10	15	Ω	I _{OUT} = 10mA, V _{DD} = 18V
R _{OL}	Low Output Resistance	_	6	10	Ω	I _{OUT} = 10mA, V _{DD} = 18V
I _{PK}	Peak Output Current	_	1.5	_	Α	
Switching	Time (Note 1)					
t _R	Rise Time		_	30	nsec	Figure 3-1, Figure 3-2
t _F	Fall Time	_	_	30	nsec	Figure 3-1, Figure 3-2
t _{D1}	Delay Time	_	_	50	nsec	Figure 3-1, Figure 3-2
t _{D2}	Delay Time	_	_	75	nsec	Figure 3-1, Figure 3-2
Power Sup	ply			•		•
I _S	Power Supply Current	_	_	8	mA	V _{IN} = 3V (Both Inputs)
		_	_	0.4		$V_{IN} = 0V$ (Both Inputs)

Note 1: Switching times ensured by design.

TC426/TC427/TC428 ELECTRICAL SPECIFICATIONS (CONTINUED)

Electric	al Characteristics: Over operating to	emperature range v	vith 4.5V ≤	V _{DD} ≤ 18V,	unless oth	erwise noted.
Input						
V _{IH}	Logic 1, High Input Voltage	2.4	_	_	V	
V _{IL}	Logic 0, Low Input Voltage	_		0.8	V	
I _{IN}	Input Current	-10	_	10	μΑ	$0V \le V_{IN} \le V_{DD}$
Output						
V _{OH}	High Output Voltage	V _{DD} – 0.025	_	_	V	
V_{OL}	Low Output Voltage	_		0.025	V	
R _{OH}	High Output Resistance	_	13	20	Ω	I _{OUT} = 10mA, V _{DD} = 18V
R _{OL}	Low Output Resistance	_	8	15	Ω	I _{OUT} = 10mA, V _{DD} = 18V
Switchi	ng Time (Note 1)					
t _R	Rise Time	_	_	60	nsec	Figure 3-1, Figure 3-2
t _F	Fall Time	_		60	nsec	Figure 3-1, Figure 3-2
t _{D1}	Delay Time	_		75	nsec	Figure 3-1, Figure 3-2
t _{D2}	Delay Time	_		120	nsec	Figure 3-1, Figure 3-2
Power S	Supply			•		<u> </u>
I _S	Power Supply Current	_	_	12	mA	V _{IN} = 3V (Both Inputs)
		_	l	0.6		V _{IN} = 0V (Both Inputs)

Note 1: Switching times ensured by design.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

TABLE 2-1: PIN FUNCTION TABLE

Pin No. (8-Pin PDIP, SOIC, CERDIP)	Symbol	Description
1	NC	No Internal Connection.
2	IN A	Control Input A, TTL/CMOS compatible logic input.
3	GND	Ground.
4	IN B	Control Input B, TTL/CMOS compatible logic input.
5	OUT B	CMOS totem-pole output.
6	V_{DD}	Supply input, 4.5V to 18V.
7	OUT A	CMOS totem-pole output.
8	NC	No internal Connection.

3.0 APPLICATIONS INFORMATION

3.1 Supply Bypassing

Charging and discharging large capacitive loads quickly requires large currents. For example, charging a 1000pF load to 18V in 25nsec requires an 0.72A current from the device power supply.

To ensure low supply impedance over a wide frequency range, a parallel capacitor combination is recommended for supply bypassing. Low-inductance ceramic disk capacitors with short lead lengths (< 0.5 in.) should be used. A $1\mu F$ film capacitor in parallel with one or two $0.1\mu F$ ceramic disk capacitors normally provides adequate bypassing.

3.2 Grounding

The TC426 and TC428 contain inverting drivers. Ground potential drops developed in common ground impedances from input to output will appear as negative feedback and degrade switching speed characteristics.

Individual ground returns for the input and output circuits or a ground plane should be used.

3.3 Input Stage

The input voltage level changes the no-load or quiescent supply current. The N-channel MOSFET input stage transistor drives a 2.5mA current source load. With a logic "1" input, the maximum quiescent supply current is 8mA. Logic "0" input level signals reduce quiescent current to 0.4mA maximum. Minimum power dissipation occurs for logic "0" inputs for the TC426/TC427/TC428. **Unused driver inputs must be connected to V**_{DD} or GND.

The drivers are designed with 100mV of hysteresis. This provides clean transitions and minimizes output stage current spiking when changing states. Input voltage thresholds are approximately 1.5V, making the device TTL compatible over the 4.5V to 18V supply operating range. Input current is less than $1\mu\text{A}$ over this range.

The TC426/TC427/TC428 may be directly driven by the TL494, SG1526/1527, SG1524, SE5560, and similar switch-mode power supply integrated circuits.

3.4 Power Dissipation

The supply current vs frequency and supply current vs capacitive load characteristic curves will aid in determining power dissipation calculations.

The TC426/TC427/TC428 CMOS drivers have greatly reduced quiescent DC power consumption. Maximum quiescent current is 8mA compared to the DS0026 40mA specification. For a 15V supply, power dissipation is typically 40mW.

Two other power dissipation components are:

- Output stage AC and DC load power.
- · Transition state power.

Output stage power is:

$$Po = P_{DC} + PAC$$
$$= Vo (I_{DC}) + f C_L V_S^2$$

Where:

Vo = DC output voltage
I_{DC} = DC output load current
f = Switching frequency
Vs = Supply voltage

In power MOSFET drive applications the P_{DC} term is negligible. MOSFET power transistors are high impedance, capacitive input devices. In applications where resistive loads or relays are driven, the P_{DC} component will normally dominate.

The magnitude of P_{AC} is readily estimated for several cases:

During output level state changes, a current surge will flow through the series connected N and P channel output MOSFETS as one device is turning "ON" while the other is turning "OFF". The current spike flows only during output transitions. The input levels should not be maintained between the logic "0" and logic "1" levels. Unused driver inputs must be tied to ground and not be allowed to float. Average power dissipation will be reduced by minimizing input rise times. As shown in the characteristic curves, average supply current is frequency dependent.

FIGURE 3-1: INVERTING DRIVER SWITCHING TIME TEST CIRCUIT

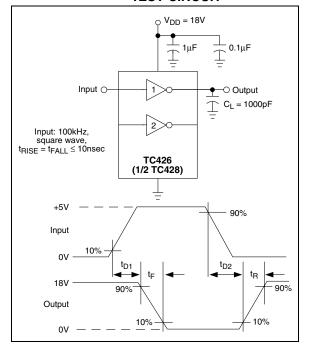


FIGURE 3-2: NONINVERTING DRIVER SWITCHING TIME

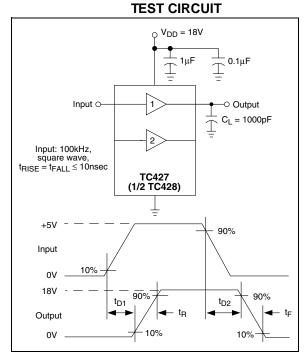


FIGURE 3-3: VOLTAGE DOUBLER

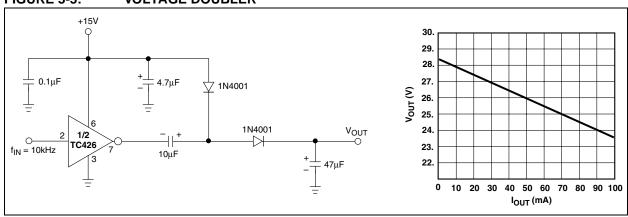
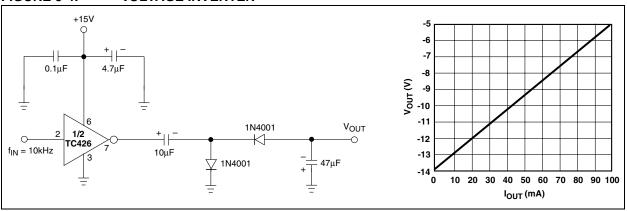
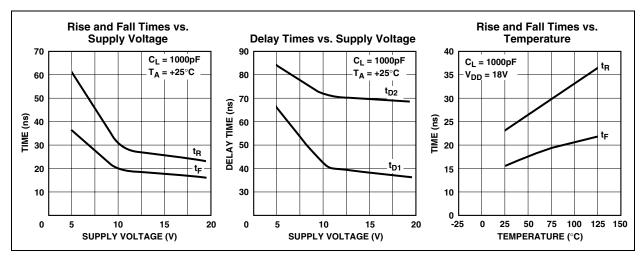


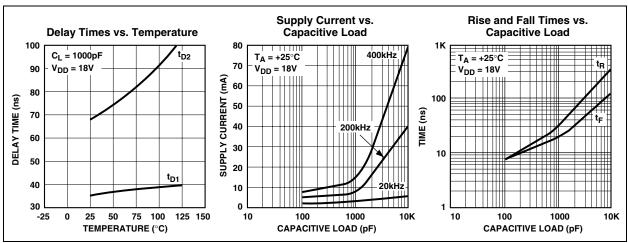
FIGURE 3-4: VOLTAGE INVERTER

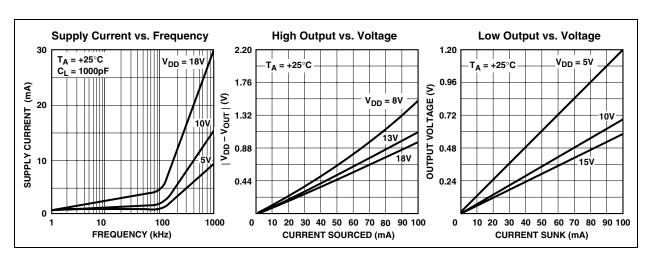


4.0 TYPICAL CHARACTERISTICS

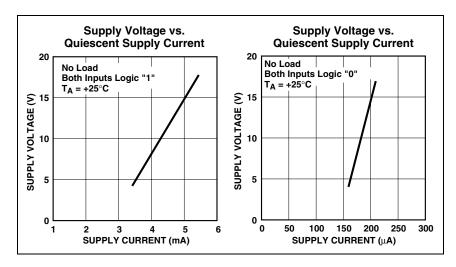
Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

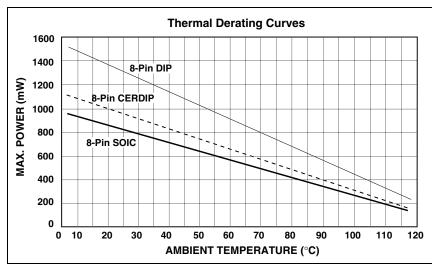






TYPICAL CHARACTERISTICS (CONTINUED)



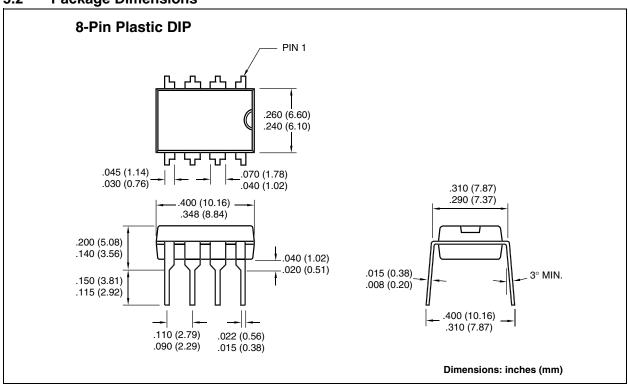


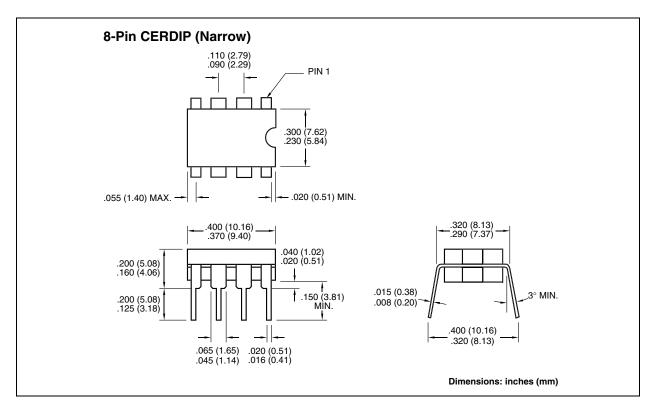
5.0 PACKAGING INFORMATION

5.1 Package Marking Information

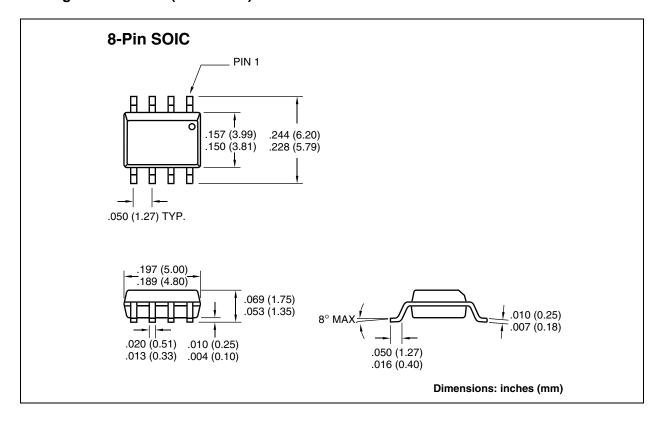
Package marking data not available at this time.

5.2 Package Dimensions





Package Dimensions (Continued)



NOTES:

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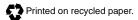
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